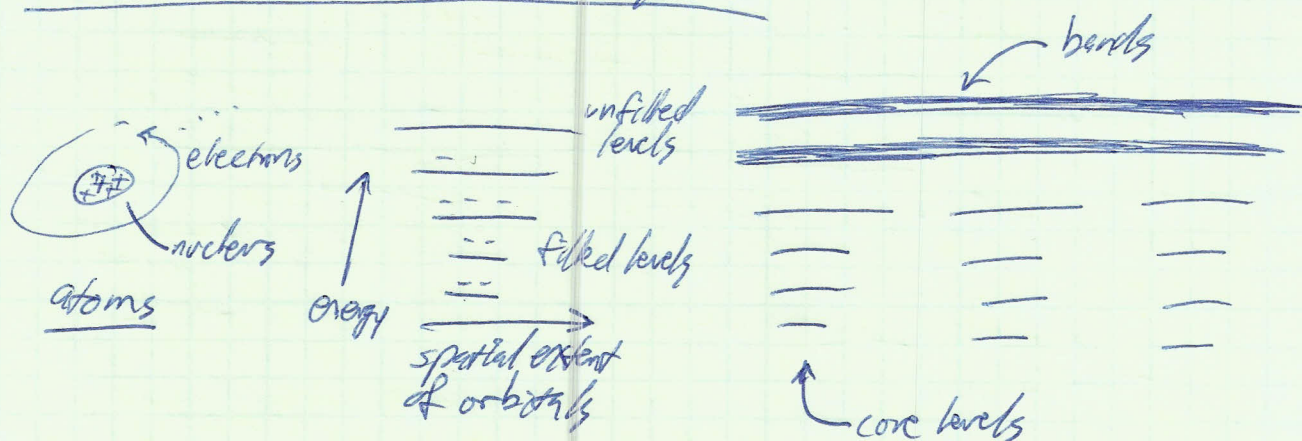
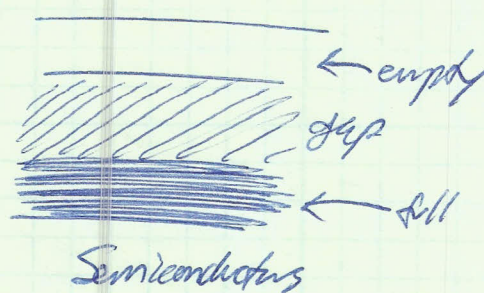
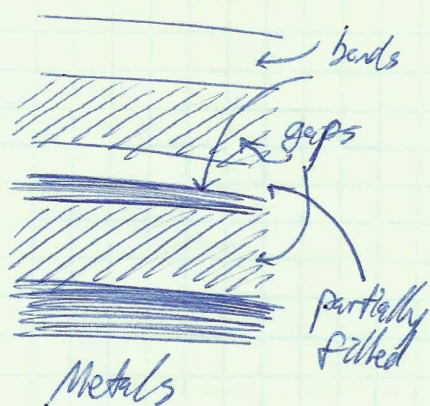


Diodes

Basic Semiconductor Physics



- Electrons in the atom can occupy discrete states
- In a solid crystal, the upper states merge into bands
- Properties of solids depend on these bands

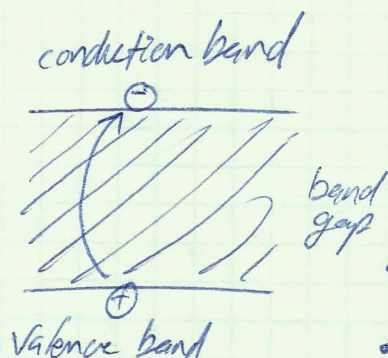


also cover
0 K, 300 K,
(semiconductors)
and insulators

- Conducting current means electrons moving within the band
- if the band is full, there is no net current

Most semiconductors are group IV : C, Ge, Si

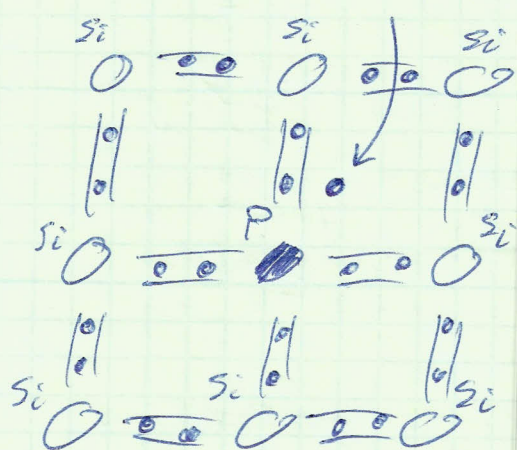
or III-V : GaAs, InP, AlGaAs, GaN, etc.



- Thermal excitation promotes some electrons from lower (valence) band to upper (conduction) band leaving a hole.
- Both electron and hole can move (conducts electricity)
- Carrier densities:
 - Metals $\sim 10^{28} - 10^{29} \text{ cm}^{-3}$
 - Semiconductors $\sim 10^{16} - 10^{19} \text{ cm}^{-3}$
 - Insulators $\sim 10^7 \text{ cm}^{-3}$

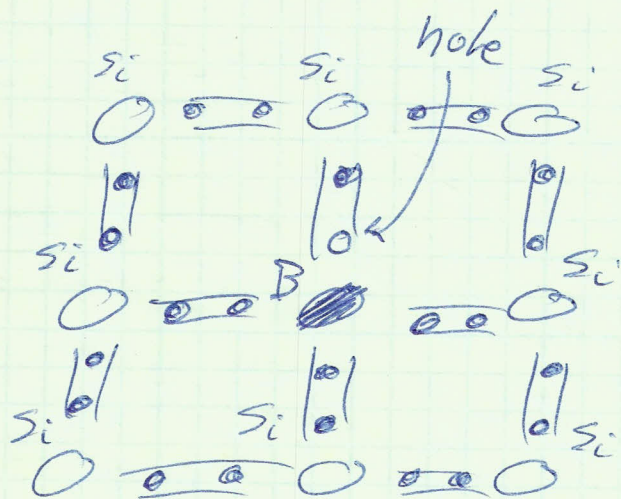
• Insulators are just like semiconductors, but with a much larger gap

• Doped semiconductors: extra electron



n-type semiconductor

Add group V elements



p-type semiconductor

Add group III elements

Thermal excitation of carriers

$n = p = n_i$ (in intrinsic - undoped - semiconductor)

$$n_i = BT^{3/2} e^{-E_g/2kT} \quad T = \text{temperature}$$

$\uparrow$ material-dependent constant
 $\uparrow$ band gap energy

equal numbers of electrons + holes

for any semiconductor (even doped) $n \cdot p = n_i^2$

Doped Semiconductors

(in thermal equilibrium)

• Balance between thermal generation and recombination

N_D = density of donors

N_A = density of acceptors

for n-type:

$$p_n n_n = n_i^2, \quad n_n \approx N_D \rightarrow p_n \approx \frac{n_i^2}{N_D}$$

for p-type

$$p_p n_p = n_i^2, \quad p_p \approx N_A \rightarrow n_p \approx \frac{n_i^2}{N_A}$$

$\uparrow$ majority carriers
 $\uparrow$ minority carriers

Current flow in Semiconductors

• Drift current - motion in response to electric field

$$v_{p\text{-drift}} = \mu_p E \leftarrow \text{electric field}$$

$\uparrow$ mobility (material dependent)
 $\uparrow$ drift velocity of holes

$$v_{n\text{-drift}} = \mu_n E$$

Drift Current - continued

$$J = q(p\mu_p + n\mu_n)E$$

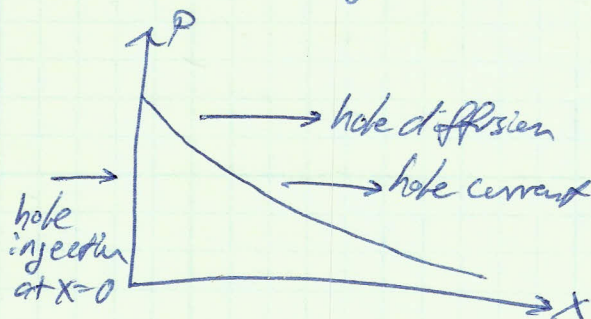
↑ ↑ carrier densities
electronic charge

$$J = \sigma E \rightarrow \sigma = q(p\mu_p + n\mu_n) \text{ conductivity}$$

• Diffusion current - motion due to concentration gradient

$$J_p = -qD_p \frac{dp(x)}{dx}$$

↑
diffusion constant
(material dependent)

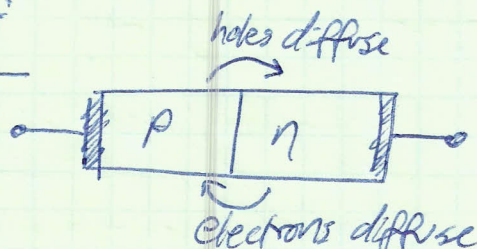


$$J_n = qD_n \frac{dn(x)}{dx}$$

Relationship between D and μ : $\frac{D_n}{\mu_n} = \frac{D_p}{\mu_p} = V_T = \frac{kT}{q}$
(not derived here)

↑ thermal voltage

Junction Diode:



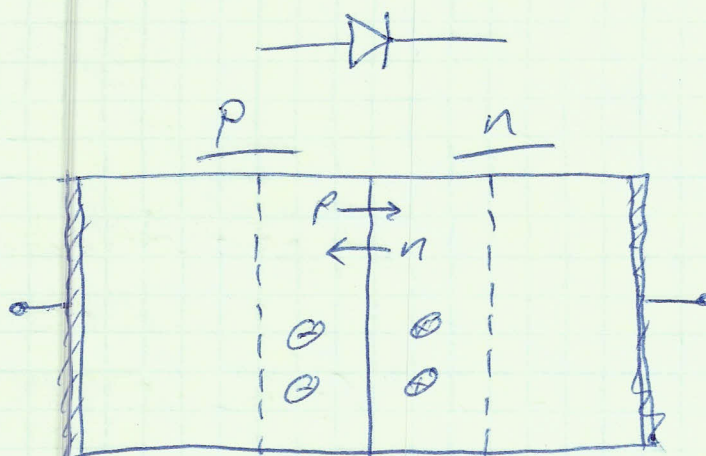
Potential barrier →



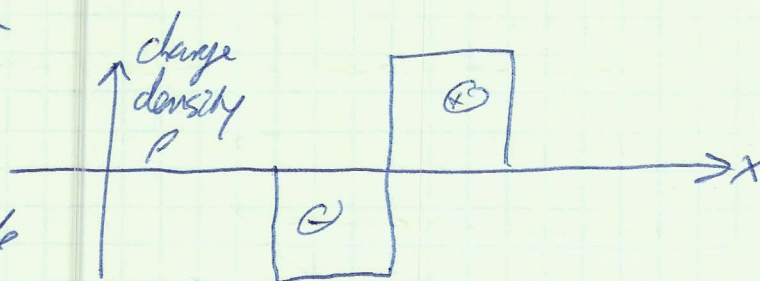
Carriers diffuse to the opposite side and deplete majority carriers near the junction
- called "depletion region"
- creates "built-in voltage" that counters the flow of charge

The Junction Diode

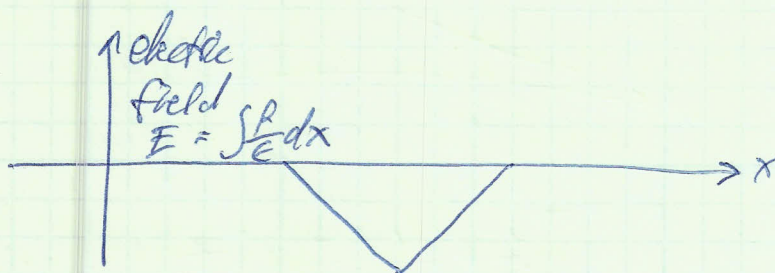
- holes diffuse to n-side
- electrons diffuse to p-side
- these minority carriers recombine, and deplete the majority carriers in a narrow ($\sim 0.5 \mu\text{m}$) region called "depletion region"



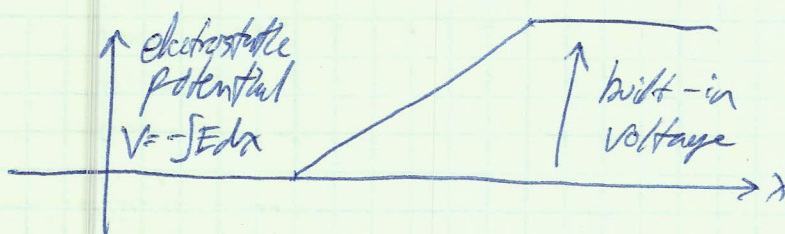
- Width is related to dopant density in each side



- Charge density creates electric field in depletion region, and built-in voltage



- Charge is not due to presence of diffused minority carriers (which have recombined) but due to "unpaired" ions that are exposed

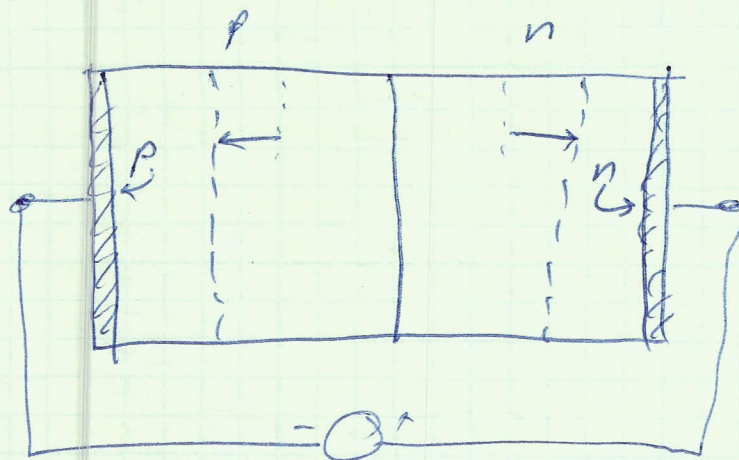
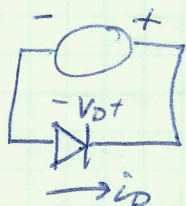


- This cannot be used as a battery or voltage source.

- if attached to a load with no other sources, there will be other voltage drops such as across the contacts, so no current will flow

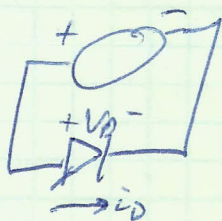
I-V characteristics of Diodes

• Reverse Bias



- Some majority carriers flow to the terminals
- p-side becomes more negatively charged, n-side becomes more positively charged
- width of depletion region becomes wider
- potential barrier becomes higher
- no majority carriers can cross the depletion region
- a small current will flow due to minority carriers
 - called "saturation current", typically $\sim 10^{-9} \text{ A}$ (nA)
 - $i_D = -I_S$
 - I_S is temperature dependent - related to thermal electron-hole pair production
 - I_S doubles every $\sim 7^\circ \text{C}$ in temperature

• Forward Bias



- majority carriers move toward depletion region
- depletion region gets narrower
- potential barrier is reduced
- at high enough voltage, carriers can flow through the depletion region

$$I_D = I_S (e^{V_D/nV_T} - 1)$$

reverse current due to minority carriers
 $V_T = kT/q \approx 26 \text{ mV at } T = 300 \text{ K}$

• note at $V_D = 0$,
 $I_D = I_S (1 - 1) = 0$

$$q = 1.6 \times 10^{-19} \text{ C}$$

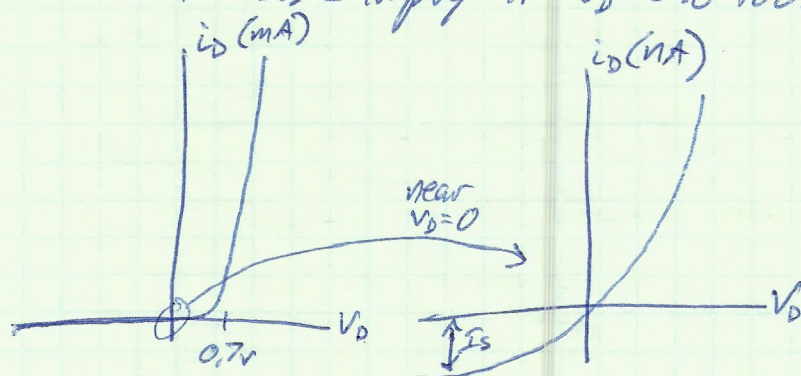
$$k = 1.38 \times 10^{-23} \text{ J/K}$$

n = emission coefficient

($n = 2$ for Si diodes, $1 \leq n \leq 2$ in ICs)

I_S is $\sim \text{nA}$ range

Although I_S is very small, $e^{V_D/0.05}$ compensates,
 current rises sharply at $V_D = 0.6$ to 0.7 V



Power $P = I_D V_D$ is dissipated as heat

if high enough currents this can damage the diode

Reverse Breakdown

- At high enough bias voltage, minority carriers are accelerated through the depletion region
- Impact ionization can create new electron-hole pairs
- Avalanche process leads to sharp increase in current
- Can destroy the diode (except Zener diodes)